L Number	Hits	Search Text	DB	Time stamp
1	7311	(encapsulat$4 or mold$4) and semiconductor and clean$3	USPAT	2003/06/04 14:13
2	75	(encapsulat$4 or mold$4) and semiconductor and clean$3 and silica adj filler$1	USPAT	2003/06/04 15:49
3	20	(encapsulat$4 or mold$4) and semiconductor and silica near3 volume near3 (percent or "%")	USPAT	2003/06/04 16:18
4	4	(encapsulat$4 or mold$4) and semiconductor and silica near3 volume near3 (percent or "%")	US-PGPUB	2003/06/04 16:18
5	183	(encapsulat$4 or mold$4) and semiconductor and silica near3 filler	US-PGPUB	2003/06/04 16:06
6	91	(encapsulat$4 or mold$4) and semiconductor and silica near filler	US-PGPUB	2003/06/04 16:07
7	1	(encapsulat$4 or mold$4) and semiconductor and silica near filler and gotou	US-PGPUB	2003/06/04 16:07
8	4	(encapsulat$4 or mold$4) and semiconductor and silica near3 vol near3 (percent or "%")	US-PGPUB	2003/06/04 16:19
9	20	(encapsulat$4 or mold$4) and semiconductor and silica near3 vol near3 (percent or "%")	USPAT	2003/06/04 16:19
10	20	(encapsulat$4 or mold$4) and semiconductor and silica near3 vol near3 (percent or "%" or pct)	USPAT	2003/06/04 16:19
11	4	(encapsulat$4 or mold$4) and semiconductor and silica near3 vol near3 (percent or "%" or pct)	US-PGPUB	2003/06/04 16:19
12	3	(encapsulat$4 or mold$4) and semiconductor and silica near filler near6 vol near3 (percent or "%" or pct)	USPAT	2003/06/04 16:28
37	4	silica near filler near6 (vol or volume) near3 (percent or "%" or pct) same (weight or wt) near3 (percent or "%" or pct)	USPAT	2003/06/04 16:27